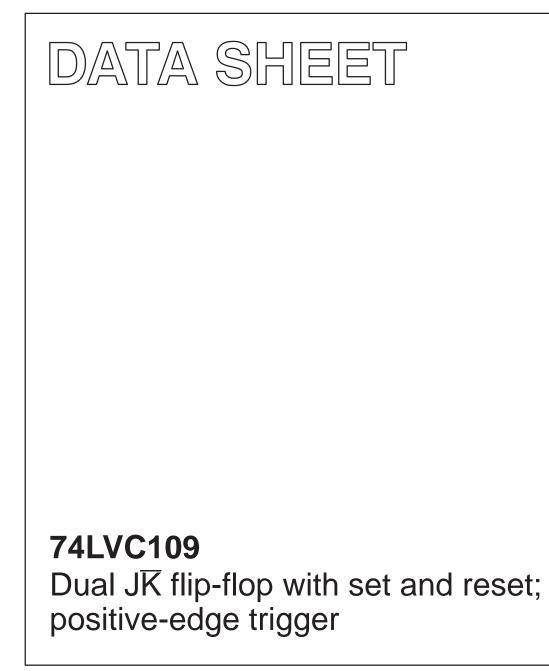
# INTEGRATED CIRCUITS



Product specification Supersedes data of 1997 Mar 18 IC24 Data Handbook

1998 Apr 28



74LVC109

#### FEATURES

- Wide supply voltage range of 1.2 to 3.6 V
- In accordance with JEDEC standard no. 8-1A.
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Output capability: standard
- I<sub>CC</sub> category: flip-flops

#### DESCRIPTION

The 74LVC109 is a low-voltage Si-gate CMOS device that is pin and function compatible with 74HC/HCT109.

The 74LVC109 is a dual positive-edge triggered J $\overline{K}$ -type flip-flop featuring individual J,  $\overline{K}$  inputs, clock (CP) inputs, set ( $\overline{S}_D$ ) and reset ( $\overline{R}_D$ ) inputs; also complementary Q and  $\overline{Q}$  outputs.

The set and reset are asynchronous active LOW inputs and operate independently of the clock input.

The J and  $\overline{K}$  inputs control the state changes of the flip-flops as described in the mode select function table. The J and  $\overline{K}$  inputs must be stable one set-up time prior to the LOW-to-HIGH clock transition for predictable operation. The J $\overline{K}$  design allows operation as a D-type flip-flop by tying the J and  $\overline{K}$  inputs together.

Schmitt-trigger action in the clock input makes the circuit highly tolerant to slower clock rise and fall times.

### QUICK REFERENCE DATA

#### GND = 0 V; $T_{amb} = 25^{\circ}C$ ; $t_r = t_f \le 2.5$ ns

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t <sub>PHL</sub> /t <sub>PLH</sub>	$\begin{array}{l} Propagation \ delay \\ nCP \ to \ nQ, \ n\overline{Q} \\ n\overline{S}_D \ to \ nQ, \ n\overline{Q} \\ n\overline{R}_D \ to \ nQ, \ n\overline{Q} \end{array}$	C <sub>L</sub> = 50 pF; V <sub>CC</sub> = 3.3 V	4.0 4.5 4.5	ns
f <sub>max</sub>	Maximum clock frequency		250	MHz
CI	Input capacitance		5.0	pF
C <sub>PD</sub>	Power dissipation capacitance per flip-flop	$V_{I} = GND \text{ to } V_{CC}^{1}$	27	pF

#### NOTE:

1. C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in  $\mu$ W) P<sub>D</sub> = C<sub>PD</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>i</sub> +  $\Sigma$  (C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) where: f<sub>i</sub> = input frequency in MHz; C<sub>L</sub> = output load capacity in pF; f<sub>0</sub> = output frequency in MHz; V<sub>CC</sub> = supply voltage in V;

 $\Sigma (C_L \times V_{CC}^2 \times f_0) =$  sum of the outputs.

#### **ORDERING INFORMATION**

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
16-Pin Plastic SO	-40°C to +85°C	74LVC109 D	74LVC109 D	SOT109-1
16-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC109 DB	74LVC109 DB	SOT338-1
16-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC109 PW	74LVC109PW DH	SOT403-1

#### **PIN CONFIGURATION**

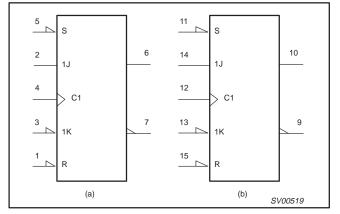
п.р. Г		16 <sup>V</sup> CC
1J 2		15 2 <sup>R</sup> D
1 <del>K</del> 3		14 2J
1CP 4		13 2K
18 <sub>D</sub> 5		12 2CP
1Q 6		11 2 <sup>5</sup> D
1Q 7		10 2Q
GND 8		9 2 <del>0</del>
	S	SV00517

#### **PIN DESCRIPTION**

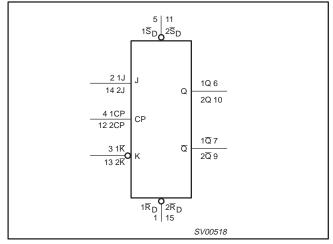
PIN NUMBER	SYMBOL	FUNCTION
1, 15	$1\overline{R}_{D}, 2\overline{R}_{D}$	Asynchronous reset input (active LOW)
2, 14, 3, 13	1J, 2J, 1 <del>K</del> , 2 <del>K</del>	Synchronous inputs; flip-flops 1 and 2
4, 12	1CP, 2CP	Clock input (LOW-to-HIGH, edge-triggered)
5, 11	$1\overline{S}_{D,}2\overline{S}_{D}$	Asynchronous set inputs (active LOW)
6, 10	1Q, 2Q	True flip-flop outputs
7, 9	1 <u>Q</u> , 2 <u>Q</u>	Complement flip-flop outputs
8	GND	Ground (O V)
16	V <sub>CC</sub>	Positive supply voltage

## 74LVC109

### LOGIC SYMBOL (IEEE/IEC)

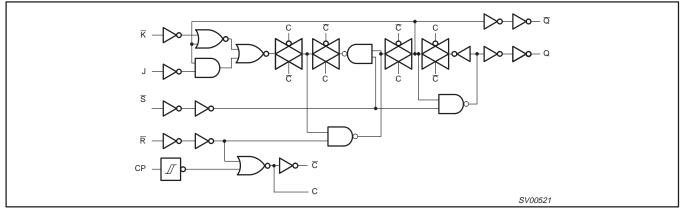


## LOGIC SYMBOL



#### **FUNCTIONAL DIAGRAM** 5 $1\overline{S}_{D}$ o S<sub>D</sub> 1J 2\_\_\_ 1Q 6 1 Q 1CP 4\_ CP FF1 1Q 7 1K Q 3\_ $R_D$ $1R_D$ 1\_ 11 2Sr $S_D$ 14 2J 2Q 10 .1 Q 12 2CP CP FF2 2<del>Q</del>9 13 2K Q $R_D$ 15 2RD SV00520

## LOGIC DIAGRAM



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#### **FUNCTION TABLE**

OPERATING MODES	INPUTS					OUTPUTS		
OPERATING MODES	nS <sub>D</sub>	nR <sub>D</sub>	nCP	nJ	nK	nQ	nQ	
Asynchronous set	L	Н	Х	Х	Х	Н	L	
Asynchronous reset	Н	L	Х	Х	Х	L	н	
Undetermined	L	L	Х	Х	Х	н	н	
Toggle	Н	Н	$\uparrow$	h	I	q	q	
Load "0" (reset)	Н	Н	$\uparrow$	1	I	Ĺ	Н	
Load "1" (set)	Н	Н	$\uparrow$	h	h	Н	L	
Hold "no change"	Н	Н	$\uparrow$	I	h	q	q	

#### NOTES:

H = HIGH voltage level

h = HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition

L = LOW voltage level

I = LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition

q = lower case letters indicate the state of the referenced output one set-up time prior to the LOW-to-HIGH CP transition.

X = don't care

 $\uparrow$  = LOW-to-HIGH CP transition

### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	CONDITIONS	LIM	UNIT	
STWIDUL	FARAIVIETER	CONDITIONS	MIN	MAX	UNIT
)/	DC supply voltage (for max. speed performance)		2.7	3.6	V
V <sub>CC</sub>	DC supply voltage (for low-voltage applications)		1.2	3.6	v
VI	DC input voltage range		0	5.5	V
Vo	DC output voltage range		0	V <sub>CC</sub>	V
T <sub>amb</sub>	Operating free-air temperature range		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input rise and fall times	V <sub>CC</sub> = 1.2 to 2.7V V <sub>CC</sub> = 2.7 to 3.6V	0 0	20 10	ns/V

#### ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER CONDITIONS		RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +6.5	V
I <sub>IK</sub>	DC input diode current	$V_{I} < 0$	-50	mA
VI	DC input voltage	Note 2	-0.5 to +5.5	V
I <sub>OK</sub>	DC output diode current	$V_{O} > V_{CC} \text{ or } V_{O} < 0$	± 50	mA
Vo	DC output voltage	Note 2	–0.5 to V <sub>CC</sub> +0.5	V
Ι <sub>Ο</sub>	DC output source or sink current	$V_{O} = 0$ to $V_{CC}$	± 50	mA
I <sub>GND</sub> , I <sub>CC</sub>	DC V <sub>CC</sub> or GND current		±100	mA
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C
P <sub>TOT</sub>	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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#### DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

			L	LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -				
			MIN	TYP <sup>1</sup>	MAX	1	
M		$V_{CC} = 1.2V$	V <sub>CC</sub>			v	
V <sub>IH</sub>	HIGH level Input voltage	V <sub>CC</sub> = 2.7 to 3.6V	2.0			1 `	
M		V <sub>CC</sub> = 1.2V			GND	V	
V <sub>IL</sub>	LOW level Input voltage	V <sub>CC</sub> = 2.7 to 3.6V			0.8	1 `	
V <sub>OH</sub>		$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -12mA$	V <sub>CC</sub> -0.5				
	HIGH level output voltage	$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -100\mu A$	V <sub>CC</sub> -0.2	V <sub>CC</sub>		v	
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -12mA$	V <sub>CC</sub> -0.6			l v	
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -24mA$	V <sub>CC</sub> -1.0			1	
		$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 12mA$			0.40		
V <sub>OL</sub>	LOW level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		GND	0.20	V	
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 24mA$			0.55	1	
ł	Input leakage current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = 5.5V or GND		±0.1	±5	μA	
I <sub>CC</sub>	Quiescent supply current	$V_{CC} = 3.6V; V_I = V_{CC} \text{ or GND}; I_O = 0$		0.1	10	μA	
$\Delta I_{CC}$	Additional quiescent supply current per input pin	$V_{CC}$ = 2.7V to 3.6V; $V_{\rm I}$ = $V_{CC}$ –0.6V; $I_{\rm O}$ = 0		5	500	μΑ	

NOTE:

1. All typical values are at V\_{CC} = 3.3V and T\_{amb} = 25°C.

### AC CHARACTERISTICS

GND = 0 V;  $t_r$  =  $t_f$   $\leq~$  2.5 ns; CL = 50 pF; RL = 500 $\Omega;$  Tamb = -40°C to +85°C

					LIM	ITS			
SYMBOL PARAMETER		WAVEFORM	VAVEFORM $V_{CC} = 3.3V \pm 0.3V$			V <sub>CC</sub> = 2.7V			UNIT
			MIN	TYP <sup>1</sup>	МАХ	MIN	TYP NO TAG	МАХ	
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay nCP to nQ, nQ	Figures 1, 3		4.3	7.5			8.5	ns
t <sub>PLH</sub>	Propagation delay nS <sub>D</sub> to nQ nR <sub>D</sub> to nQ	Figures 2, 3		4.5	8.0			9.0	ns
t <sub>PHL</sub>	Propagation delay nS <sub>D</sub> to nQ nR <sub>D</sub> to nQ	Figures 2, 3		5.2	9.0			10	ns
t <sub>W</sub>	Clock pulse width HIGH or LOW	Figure 1	3.3	2.0					ns
t <sub>W</sub>	Set or reset pulse width HIGH or LOW	Figure 2	3.0						ns
t <sub>rem</sub>	Removal time nS <sub>D,</sub> nR <sub>D</sub> to nCP	Figure 2	3.0						ns
t <sub>su</sub>	Set-up time nJ, nK to CP	Figure 1	2.5						ns
t <sub>h</sub>	Hold time nJ, nK to nCP	Figure 1	2.0						ns
f <sub>max</sub>	Maximum clock pulse frequency	Figure 1	150	225					MHz

NOTE:

1. These typical values are at  $V_{CC}$  = 3.3V and  $T_{amb}$  = 25°C.

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#### AC WAVEFORMS

 $V_M$  = 1.5 V at  $V_{CC} \ge 2.7$  V;  $V_M$  = 0.5 ×  $V_{CC}$  at  $V_{CC} < 2.7$  V.  $V_{OL}$  and  $V_{OH}$  are the typical output voltage drop that occur with the output load.

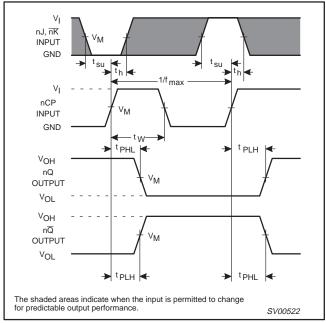


Figure 1. Clock (nCP) to output (nQ, nQ) propagation delays, the clock pulse width, the nJ and nK to nCP set-up, the nCP to nJ, nK hold times and the maximum clock pulse frequency.

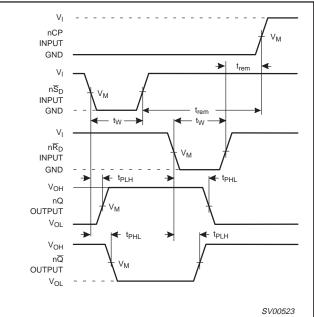
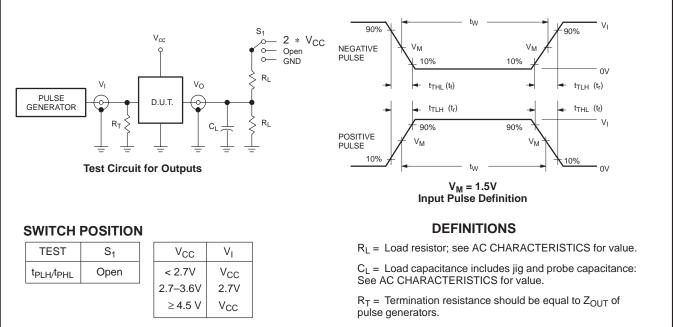


Figure 2. Set  $(n\overline{S}_D)$  and reset  $(n\overline{R}_D)$  input to output  $(nQ, n\overline{Q})$ propagation delays, the set and reset pulse widths and the  $n\overline{R}_D$ ,  $n\overline{S}_D$  to nCP removal time.

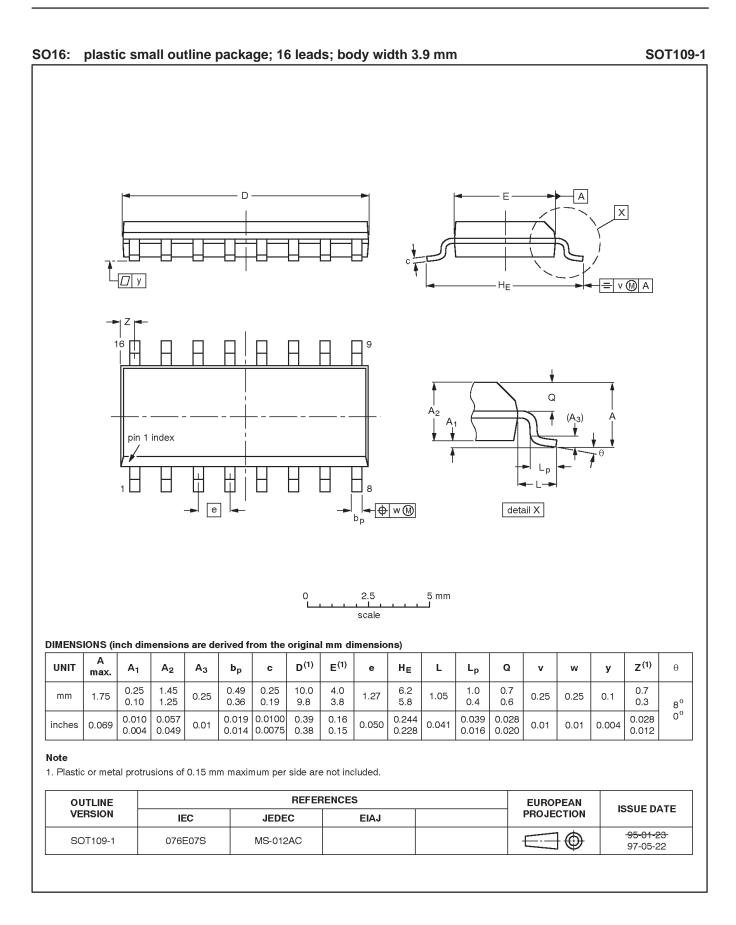
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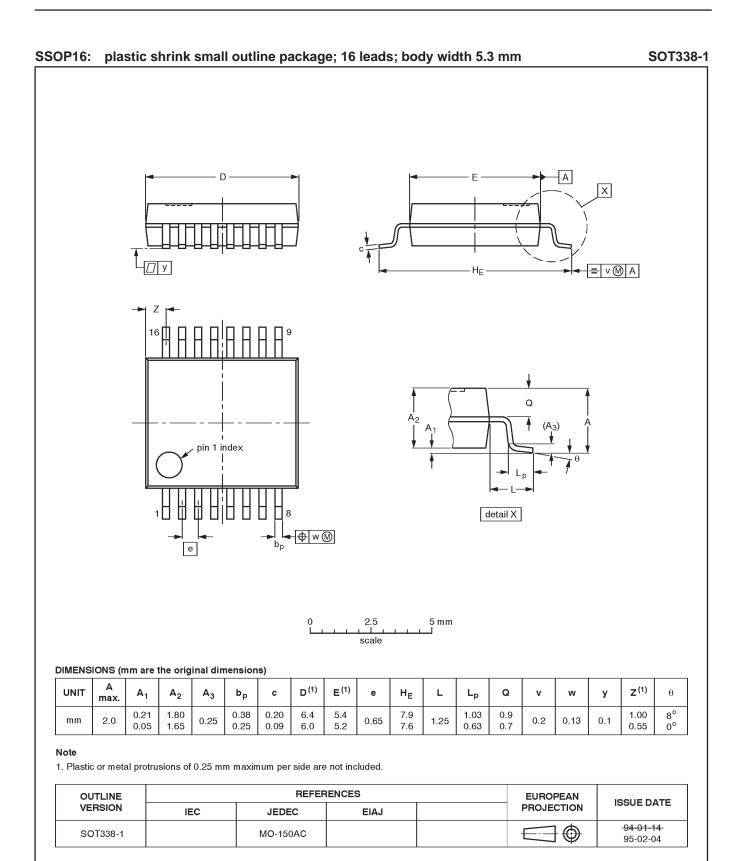
# TEST CIRCUIT

Figure 3. Load circuitry for switching times.

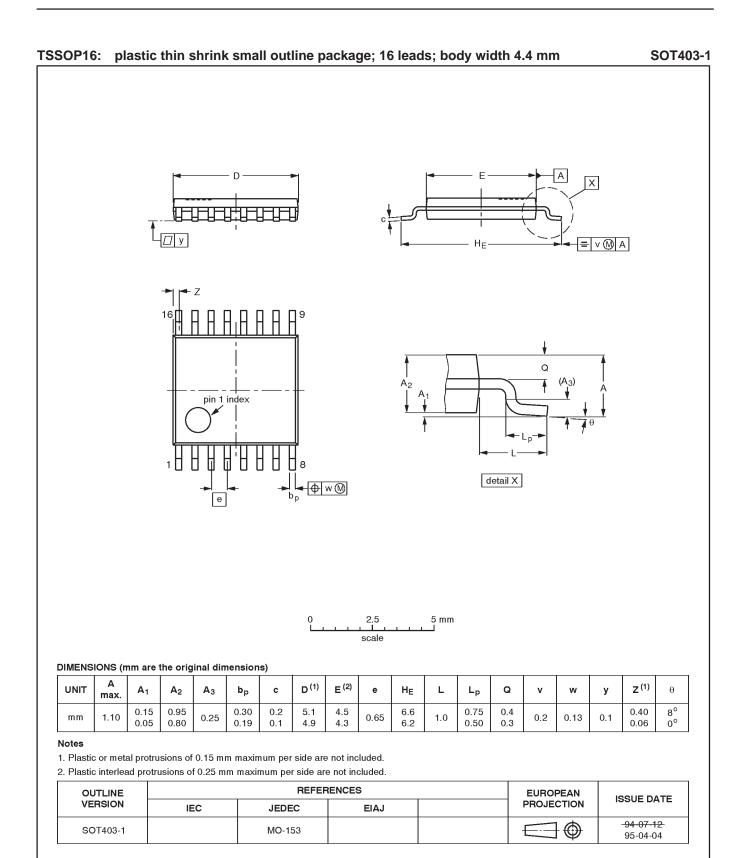
# 74LVC109



## 74LVC109



## 74LVC109



## 74LVC109

	DEFINITIONS						
Data Sheet Identification	Definition						
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